

# Bill of Materials

TI DESIGNS  
PMP8904 - MINI POL

DESIGNATOR	QUANTITY	DESCRIPTION	MANUFACTURER	PART NUMBER
AA1	1	Printed Circuit Board	Any	TPS50601SPEVM-M
C100	1	CAP, CERM, 0.1uF, 25V, X7R, 10%, 0805	PRESIDIO	SR0805X7R104K1NT95#M123
C101	1	CAP, [Tantalum], 330uF, 10V, +/-20%, 6mOhm ESR, [7343]	Kemet	T541X337M010AH6720
C102	1	CAP, CERM, 0.47uF, 25V, X7R, 10%, 1209	Presidio Components	SR1209X7R474K1NT95#M123
C103	1	CAP, [Tantalum], 330uF, 10V, +/-20%, 6mOhm ESR, [7343]	Kemet	T541X337M010AH6720
C104	1	CAP, [Tantalum], 330uF, 10V, +/-20%, 6mOhm ESR, [7343]	Kemet	T541X337M010AH6720
C106	1	CAP, CERM, 0.01uF, 25V, X7R, 10%, 0603	Presidio Components	SR0603X7R103K1NT95#M123
C108	1	CAP, CERM, 680pF, 100V, X7R, 10%, 0805	Presidio components	SR0805X7R681K3NT95#M123
C109	1	CAP, CERM, 33nF, 25V, X7R, 10%, 0805	Presidio Components	SR0805X7R333K1NT95#M123
C110	1	CAP, CERM, 0.1uF, 25V, X7R, 10%, 0805	PRESIDIO	SR0805X7R104K1NT95#M123
C111	1	CAP, CERM, 0.01uF, 25V, X7R, 10%, 0603	PRESIDIO	SR0603X7R103K1NT95#M123
D101	1	Diode, Schottky, 20V, 3A, SMB	Diodes Inc.	B320B-13-F
J100	1	PCB Pin, solderless Pressfit	Mill-Max	0952-0-00-15-00-00-03-0
J101	1	PCB Pin, solderless Pressfit	Mill-Max	0952-0-00-15-00-00-03-0
J102	1	PCB Pin, solderless Pressfit	Mill-Max	0952-0-00-15-00-00-03-0
J103	1	PCB Pin, solderless Pressfit	Mill-Max	0952-0-00-15-00-00-03-0
J104	1	PCB Pin, solderless Pressfit	Mill-Max	0952-0-00-15-00-00-03-0
J105	1	PCB Pin, solderless Pressfit	Mill-Max	0952-0-00-15-00-00-03-0
J106	1	PCB Pin, solderless Pressfit	Mill-Max	0952-0-00-15-00-00-03-0
J107	1	PCB Pin, solderless Pressfit	Mill-Max	0952-0-00-15-00-00-03-0
L100	1	Inductor, composite material, , 2.2uH, 34A, 2.55mohm, SMD	Coilcraft	AE611PYA222MSZ
R100	1	RES, 10K ohm, 1%, xW, [0603]	State of the Art	M55342K12B10E0T-W
R101	1	RES, 0 ohm, x%, xW, [0805]	State of the Art, Inc	M32159B06T-W
R102	1	RES, 10 ohm, 1%, xW, [0805]	State of the Art, Inc	M55342K06B10D0T-W
R103	1	RES, 10K ohm, 1%, xW, [0603]	State of the Art	M55342K1210E0TW
R104	1	RES, 49.9 ohm, 1%, xW, [0603]	State of the Art, Inc	M55342K12B49D5T
R105	1	RES, 3.4k ohm, 1%, xW, [0603]	State of the Art	M55342K12B3E4TW
R106	1	RES, 10.1K ohm, 0.1%, xW, [0603]	State of the Art	M55342E12B10B1TW
R107	1	RES, 2.26Kohm, 1%, xW, [0603]	State of the Art	M55342K12B2E26TW
R108	1	RES, 10K ohm, 1%, xW, [0603]	State of the Art	M55342K12B10E0TW
R109	1	RES, 196K ohm, 1%, xW, [0603]	State of the Art	M55342K12B196ETW
R110	1	RES, 19.6Kohm, 0.1%, xW, [0603]	State of the Art	M55342E12B19B6TW
U100	1	A SYNCHRONOUS STEP DOWN SWIFT CONVERTER	Texas Instruments	TPS50601MHKHV
C107	0	CAP, CERM, 2700pF, 25V, X7R, 10%, 0805	Presidio Components	SR0805X7R272K1NT95#M123
D100	0	Diode, Schottky, 20V, 3A, SMB	Diodes Inc.	B320B-13-F
R111	0	RES, 49.9 ohm, 1%, 0.125W, 0805	State of the Art	M55342K06B49D9T

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